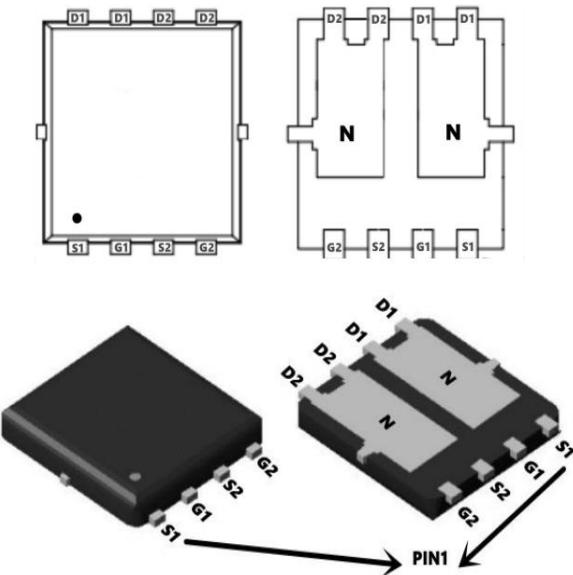


## Description

The SX30H04NF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = 40V$   $I_D = 30A$

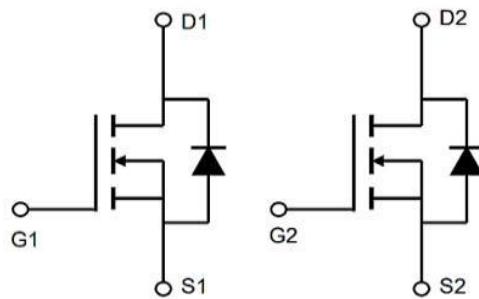
$R_{DS(ON)} < 14m\Omega$  @  $V_{GS}=10V$

## Application

Wireless charging

Boost driver

Brushless motor



## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current <sup>1</sup>	30	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current <sup>1</sup>	21	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	36	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	31	mJ
$I_{AS}$	Avalanche Current	25	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.9	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup> ( $t \leq 10s$ )	25	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-ambient <sup>1</sup>	8	°C/W

**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	44	---	V
$\Delta BVDSS/\Delta TJ$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=8\text{A}$	---	11	14	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=6\text{A}$	---	13	18	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.0	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.64	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=8\text{A}$	---	36	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2.1	---	$\Omega$
Q <sub>g</sub>	Total Gate Charge (4.5V)	$V_{DS}=20\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=8\text{A}$	---	10.7	---	nC
Qgs	Gate-Source Charge		---	3.3	---	nC
Qgd	Gate-Drain Charge		---	4.2	---	nC
Td(on)	Turn-On Delay Time	$V_{DD}=12\text{V}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$ $I_D=6\text{A}$	---	8.6	---	ns
T <sub>r</sub>	Rise Time		---	3.4	---	ns
Td(off)	Turn-Off Delay Time		---	24.8	---	ns
T <sub>f</sub>	Fall Time		---	2.2	---	ns
C <sub>iss</sub>	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1314	---	$\text{pF}$
C <sub>oss</sub>	Output Capacitance		---	120	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	88	---	
IS	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	8.5	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	34	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、EAS condition:  $T_J=25^\circ\text{C}$  ,  $V_{DD}=32\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{Mh}$ , $I_{AS}=22\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

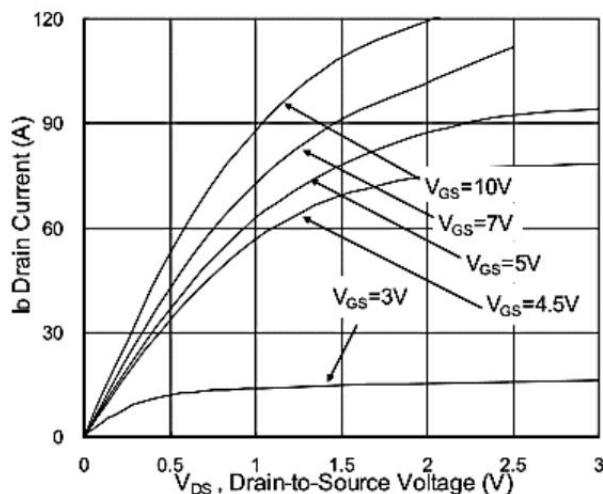


Fig.1 Typical Output Characteristics

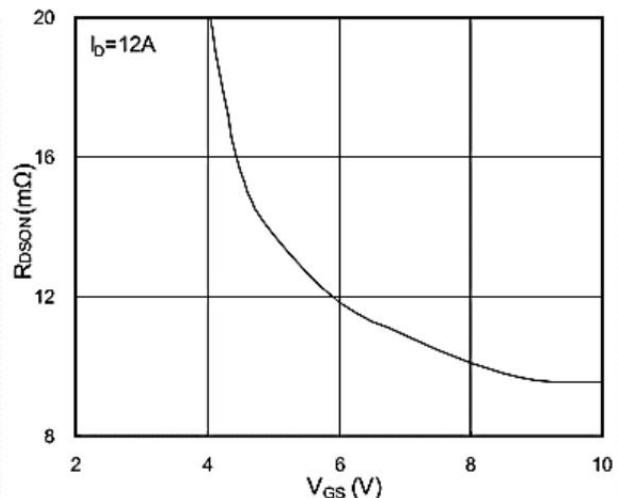


Fig.2 On-Resistance vs. G-S Voltage

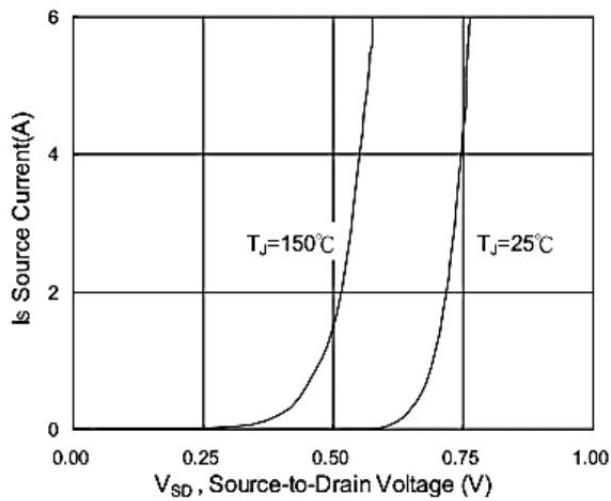


Fig.3 Forward Characteristics of Reverse

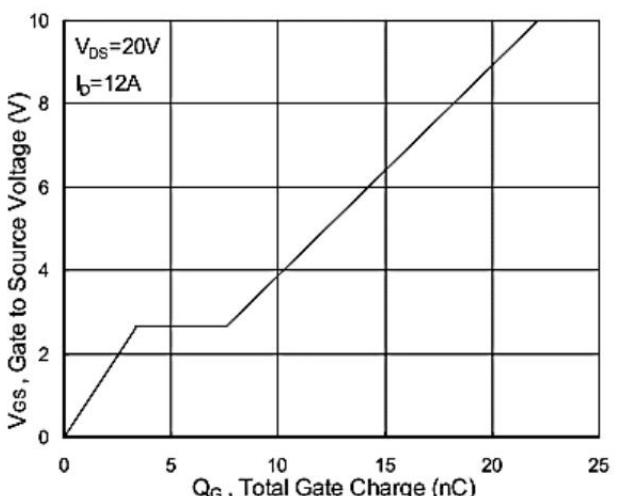


Fig.4 Gate-Charge Characteristics

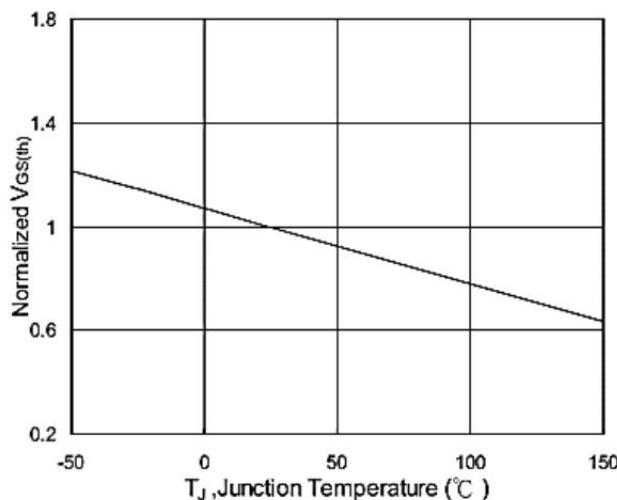


Fig.5  $V_{GS(th)}$  vs.  $T_J$

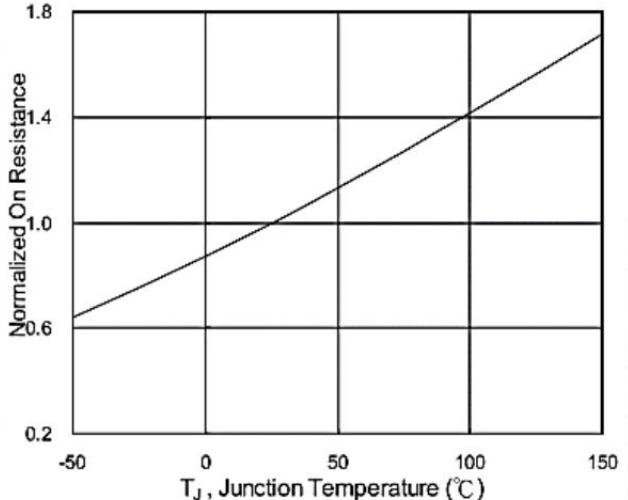
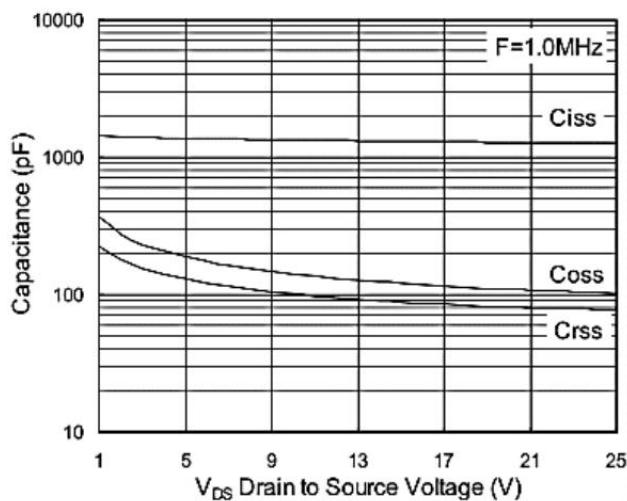
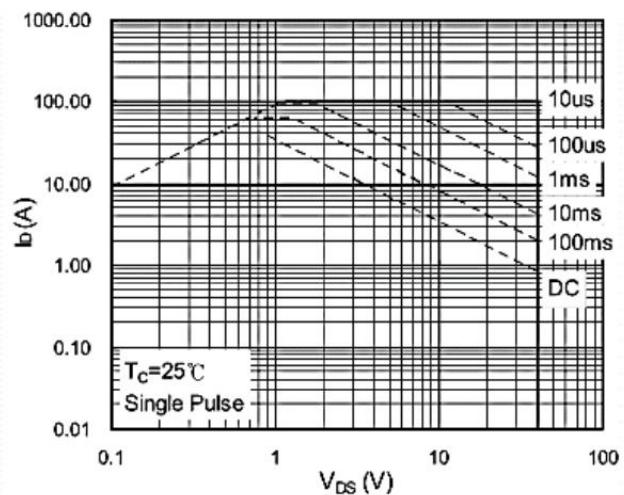


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

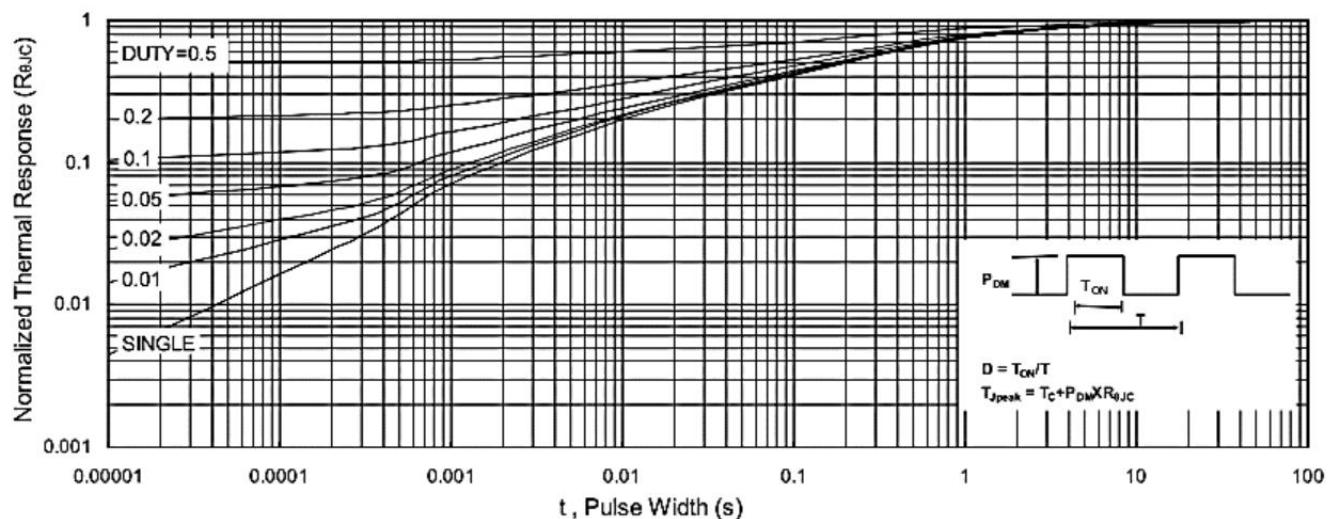
## Typical Characteristics



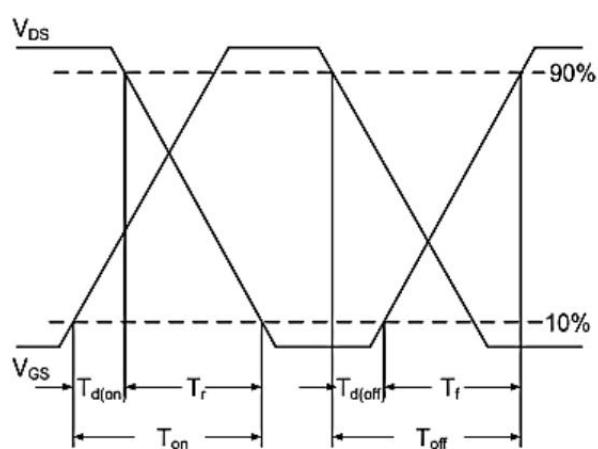
**Fig.7 Capacitance**



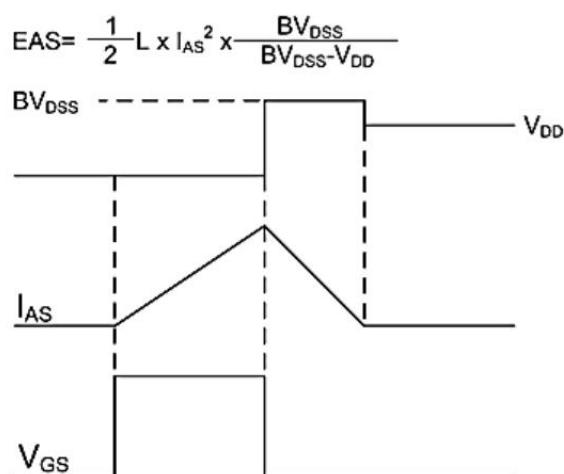
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

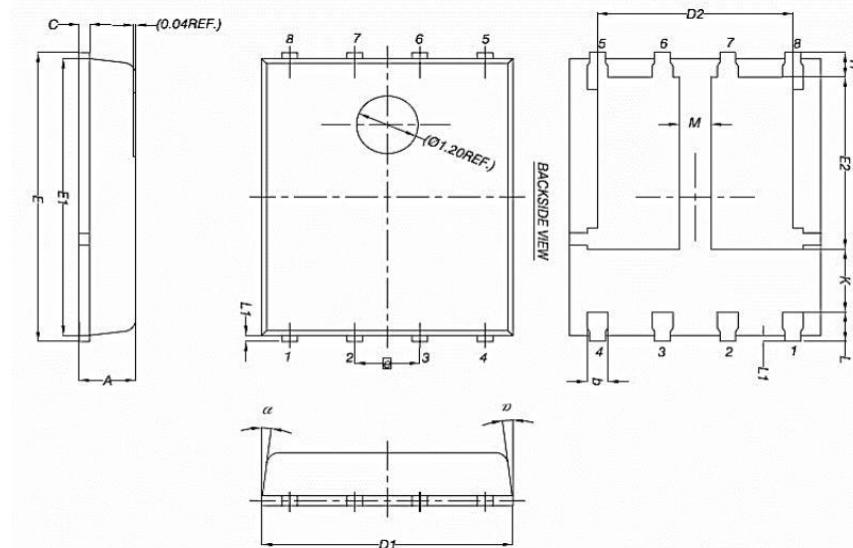


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

## Package Mechanical Data- PDFN5\*6-8L-JQ Double



Symbol	Common mm		
	Mim	Nom	Max
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	3.30	3.45
E2	3.38	3.05	3.20
e		1.27BSC	
H	0.41	0.51	0.61
K	1.10	--	--
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	--	--
a	0 °	--	12 °

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000